APA3010F3C-GX
3.0 mm x 1.0 mm Right Angle Infrared Emitting Diode

DESCRIPTION
• F3 Made with Gallium Arsenide Infrared Emitting diodes

FEATURES
• 3.0 x 2.0 x 1.0 mm right angle SMD LED, 1.0 mm thickness
• Mechanically and spectrally matched to the phototransistor
• Package: 2000 pcs / reel
• Moisture sensitivity level: 3
• Tinned pads for improved solderability
• Halogen-free
• RoHS compliant

APPLICATIONS
• Infrared Illumination for cameras
• Machine vision systems
• Surveillance systems
• Industrial electronics
• IR data transmission
• Remote control

PACKAGE DIMENSIONS

RECOMMENDED SOLDERING PATTERN
(units : mm; tolerance : ± 0.1)

Part Number | Emitting Color (Material) | Lens Type | Po (mW/sr) @ 20mA | Viewing Angle
<table>
<thead>
<tr>
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</tr>
</thead>
<tbody>
<tr>
<td>APA3010F3C-GX</td>
<td>Infrared (GaAs)</td>
<td>Water Clear</td>
<td>1.2</td>
<td>3</td>
</tr>
</tbody>
</table>

Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Radiant Intensity / luminous flux: +/-15%.
3. Radiant intensity value is traceable to CIE127-2007 standards.
**ELECTRICAL / OPTICAL CHARACTERISTICS at T<sub>A</sub>=25°C**

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Emitting Color</th>
<th>Value</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Wavelength at Peak Emission I&lt;sub&gt;F&lt;/sub&gt; = 20mA</td>
<td>λ&lt;sub&gt;peak&lt;/sub&gt;</td>
<td>Infrared</td>
<td>940</td>
<td>nm</td>
</tr>
<tr>
<td>Spectral Bandwidth at 50% Φ REL MAX I&lt;sub&gt;F&lt;/sub&gt; = 20mA</td>
<td>Δλ</td>
<td>Infrared</td>
<td>50</td>
<td>nm</td>
</tr>
<tr>
<td>Capacitance</td>
<td>C</td>
<td>Infrared</td>
<td>90</td>
<td>pF</td>
</tr>
<tr>
<td>Forward Voltage I&lt;sub&gt;F&lt;/sub&gt; = 20mA</td>
<td>V&lt;sub&gt;F&lt;/sub&gt;&lt;sup&gt;[1]&lt;/sup&gt;</td>
<td>Infrared</td>
<td>1.2</td>
<td>V</td>
</tr>
<tr>
<td>Reverse Current (V&lt;sub&gt;R&lt;/sub&gt; = 5V)</td>
<td>I&lt;sub&gt;R&lt;/sub&gt;</td>
<td>Infrared</td>
<td>-</td>
<td>10 µA</td>
</tr>
<tr>
<td>Temperature Coefficient of Wavelength I&lt;sub&gt;F&lt;/sub&gt; = 20mA, -10°C ≤ T ≤ 85°C</td>
<td>TC&lt;sub&gt;λ&lt;/sub&gt;</td>
<td>Infrared</td>
<td>0.3</td>
<td>nm/°C</td>
</tr>
<tr>
<td>Temperature Coefficient of V&lt;sub&gt;F&lt;/sub&gt; I&lt;sub&gt;F&lt;/sub&gt; = 20mA, -10°C ≤ T ≤ 85°C</td>
<td>TC&lt;sub&gt;V&lt;/sub&gt;</td>
<td>Infrared</td>
<td>-1.2</td>
<td>mV/°C</td>
</tr>
</tbody>
</table>

**ABSOLUTE MAXIMUM RATINGS at T<sub>A</sub>=25°C**

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Value</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power Dissipation</td>
<td>P&lt;sub&gt;D&lt;/sub&gt;</td>
<td>90</td>
<td>mW</td>
</tr>
<tr>
<td>Reverse Voltage</td>
<td>V&lt;sub&gt;R&lt;/sub&gt;</td>
<td>5</td>
<td>V</td>
</tr>
<tr>
<td>Junction Temperature</td>
<td>T&lt;sub&gt;j&lt;/sub&gt;</td>
<td>115</td>
<td>°C</td>
</tr>
<tr>
<td>Operating Temperature</td>
<td>T&lt;sub&gt;op&lt;/sub&gt;</td>
<td>-40 to +85</td>
<td>°C</td>
</tr>
<tr>
<td>Storage Temperature</td>
<td>T&lt;sub&gt;stg&lt;/sub&gt;</td>
<td>-40 to +85</td>
<td>°C</td>
</tr>
<tr>
<td>DC Forward Current</td>
<td>I&lt;sub&gt;F&lt;/sub&gt;</td>
<td>50</td>
<td>mA</td>
</tr>
<tr>
<td>Peak Forward Current</td>
<td>I&lt;sub&gt;FM&lt;/sub&gt;&lt;sup&gt;[1]&lt;/sup&gt;</td>
<td>1.2</td>
<td>A</td>
</tr>
<tr>
<td>Electrostatic Discharge Threshold (HBM)</td>
<td>-</td>
<td>8000</td>
<td>V</td>
</tr>
<tr>
<td>Thermal Resistance (Junction / Ambient)</td>
<td>R&lt;sub&gt;th,JA&lt;/sub&gt;&lt;sup&gt;[2]&lt;/sup&gt;</td>
<td>470</td>
<td>°C/W</td>
</tr>
<tr>
<td>Thermal Resistance (Junction / Solder point)</td>
<td>R&lt;sub&gt;th,JS&lt;/sub&gt;&lt;sup&gt;[2]&lt;/sup&gt;</td>
<td>330</td>
<td>°C/W</td>
</tr>
</tbody>
</table>

**Notes:**
1. Forward voltage: ±0.1V.
2. Wavelength value is traceable to CIE127-2007 standards.
3. Excess driving current and or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

**Notes:**
1. 1/100 Duty Cycle, 10µs Pulse Width.
2. R<sub>th,JA</sub>, R<sub>th,JS</sub>. Results from mounting on PC board FR4 (pad size ≥ 16 mm<sup>2</sup> per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/JESD633.
TECHNICAL DATA

RELATIVE INTENSITY vs. WAVELENGTH

![Graph showing relative intensity vs. wavelength](image)

SPATIAL DISTRIBUTION

![Graph showing spatial distribution](image)

INFRARED

Forward Current vs. Forward Voltage

![Graph showing forward current vs. forward voltage](image)

Radiant Intensity vs. Forward Current

![Graph showing radiant intensity vs. forward current](image)

Forward Current Derating Curve

![Graph showing forward current derating curve](image)

Radiant Intensity vs. Ambient Temperature

![Graph showing radiant intensity vs. ambient temperature](image)

REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

![Graph showing reflow soldering profile](image)

TAPE SPECIFICATIONS (units: mm)

![Diagram showing tape specifications](image)

REEL DIMENSION (units: mm)

![Diagram showing reel dimension](image)

Notes:
1. Don't cause stress to the LEDs while it is exposed to high temperature.
2. The maximum number of reflow soldering passes is 2 times.
3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.
PRECAUTIONARY NOTES

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage, customer should refer to the latest datasheet for the updated specifications.
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